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Tables of Contents	LDMOS in a sub-half micro	n smart power technolo
O- Journals & Magazines O- Conference	Zhu, R. Parthasarathy, V. Khemka, V. Bose, A. Roggenbauer, T. SPS, Motorola Inc., Mesa, AZ; This paper appears in: Power Semiconductor Devices and ICs, 2001. IS 01. Proceedings of the 13th International Symposium on	
Proceedings - Standards	06/04/2001 -06/07/2001, 2001 Location: Osaka, Japan On page(s): 403-406	<u>onai Symposiam on</u>
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O- By Author O- Basic O- Advanced	References Cited: 6 Number of Pages: xxxi+467 INSPEC Accession Number: 7092179	
	Abstract:	
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